Materials Declaration

Package	TQFP
Body Size	7 X 7
LeadCount	48
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	5.40 E-03	38869
SiO2 Filler	86	5.80 E-02	417839
Phenol Resin	5	3.37 E-03	24293
Antimony_Sb2O3	0.4	2.70 E-04	1943
Brominated Resin	0.4	2.70 E-04	1943
Carbon Black	0.2	1.35 E-04	972

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.93 E-02	355188
Ni	3	1.54 E-03	11077
Si	0.65	3.33 E-04	2400
Mg	0.15	7.69 E-05	554

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.19 E-03	8569

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.48 E-03	17822

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.07 E-03	7688

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	97780

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	4.72 E-04	3396
Ag Filler	74	1.34 E-03	9667

Package Totals

Weight (g)	PPM
1.39 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-SU-B

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ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

Materials Declaration

Package	TQFP
Body Size	7 X 7
LeadCount	48
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	5.40 E-03	38869
SiO2 Filler	86	5.80 E-02	417839
Phenol Resin	5	3.37 E-03	24293
Antimony_Sb2O3	0.4	2.70 E-04	1943
Brominated Resin	0.4	2.70 E-04	1943
Carbon Black	0.2	1.35 E-04	972

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.93 E-02	355188
Ni	3	1.54 E-03	11077
Si	0.65	3.33 E-04	2400
Mg	0.15	7.69 E-05	554

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.19 E-03	8569

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.10 E-03	15149
Pb	15	3.71 E-04	2673

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.07 E-03	7688

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	97780

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	4.72 E-04	3396
Ag Filler	74	1.34 E-03	9667

Package Totals

Weight (g)	PPM
1.39 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-SU-A

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